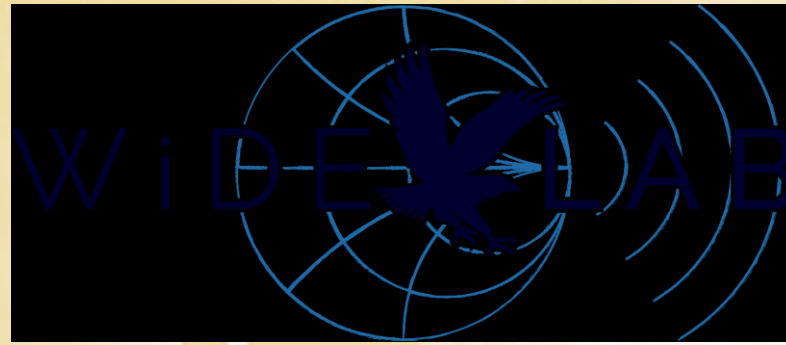


Department of Electrical, Computer,
Software and Systems Engineering



Additively Manufactured RFID-Based Passive Wireless Sensors

Eduardo Rojas-Nastrucci and Carlos R. Mejías-Morillo.

Embry-Riddle Aeronautical University, Daytona Beach, FL, 32114. E-mail:

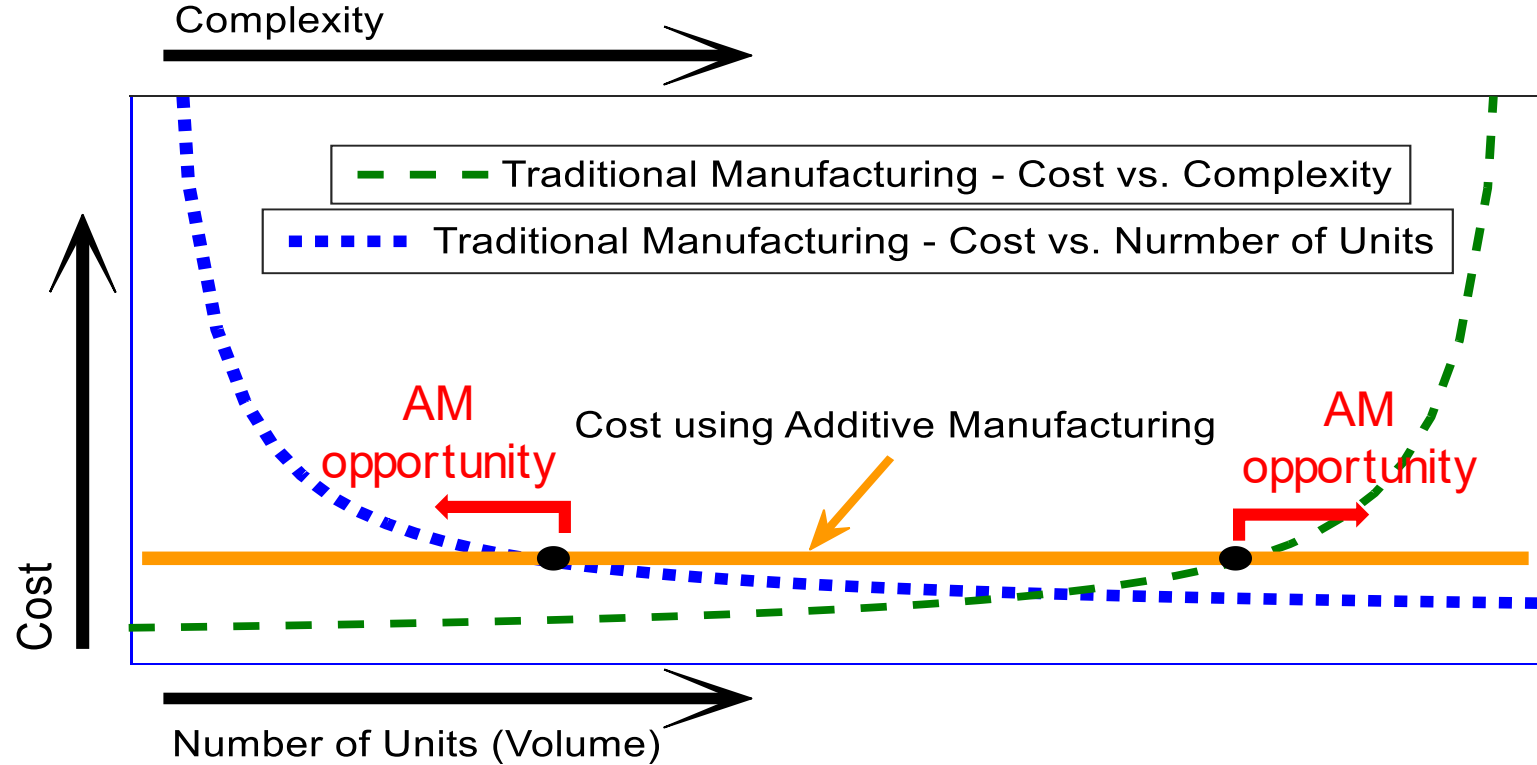
rojase1@erau.edu

Wireless Devices and Electromagnetics Laboratory

Agenda:

- ✓ *Introduction*
- ✓ *DDM Process (Additive Manufacturing)*
 - *Multilayer RF Electronics*
- ✓ *Laser Enhanced DDM*
 - *3D Component Packaging*
 - *mm-Wave Multilayer Circuit*
- ✓ *Wireless Passive Sensing for Micro Meteorite Orbital Debris (MMOD) Impacts*
- ✓ *ERAU Capabilities. Micaplex. WiDE Lab*

Introduction



**3D Printed Fuel Nozzle
(FAA Certified)**
by General Electric.

*Improved Design:
25% lighter
5x stronger
Substitutes 18 parts*



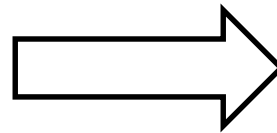
<http://www.gereports.com/post/116402870270/the-faa-cleared-the-first-3d-printed-part-to-fly/>

Simpler designs are less costly and better – Not true with AM

Evolution (Revolution)



nScript DPAM system Femtosecond Laser (10W)

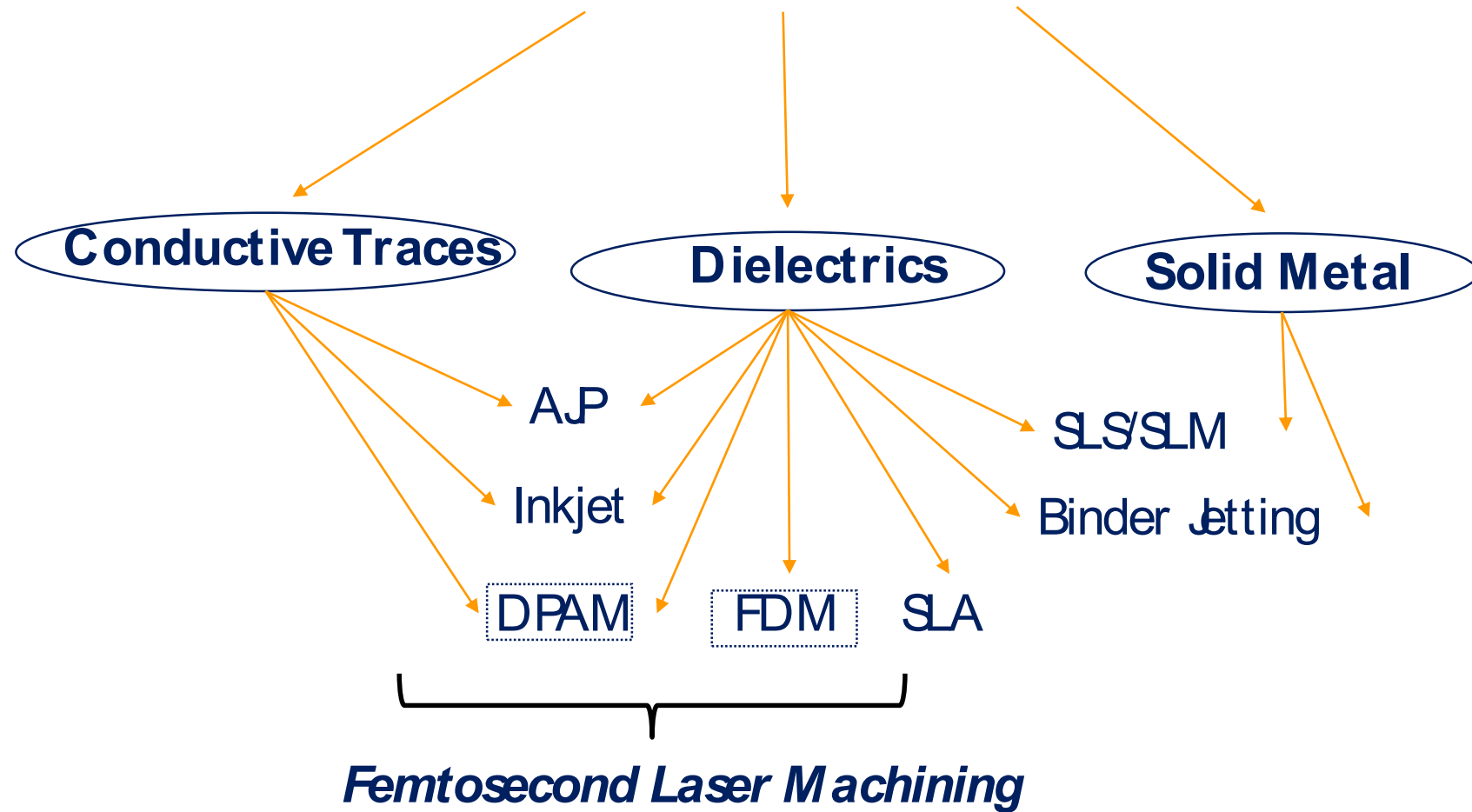


ExOne Innovent



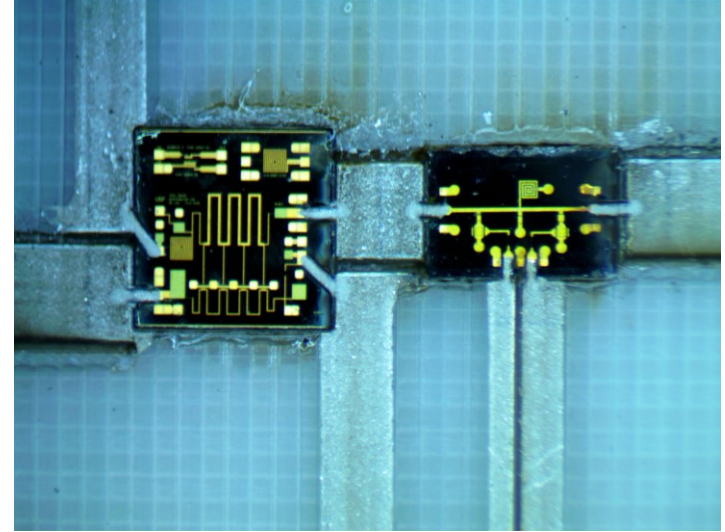
3D Printing Technologies

RF Circuits and Antennas



DDM - Introduction

- Direct Digital Manufacturing (DDM): Combination of additive and subtractive processes, *applied directly from CAD file to part*.
- This work: combination of FDM, micro-dispensing and laser machining.
 - Multiple materials, multiple layers.
 - Low temperature.
 - Match performance of Cu-clad microwave laminates.
 - Embed/integrate/package microelectronics.
 - Volumetric control of materials.

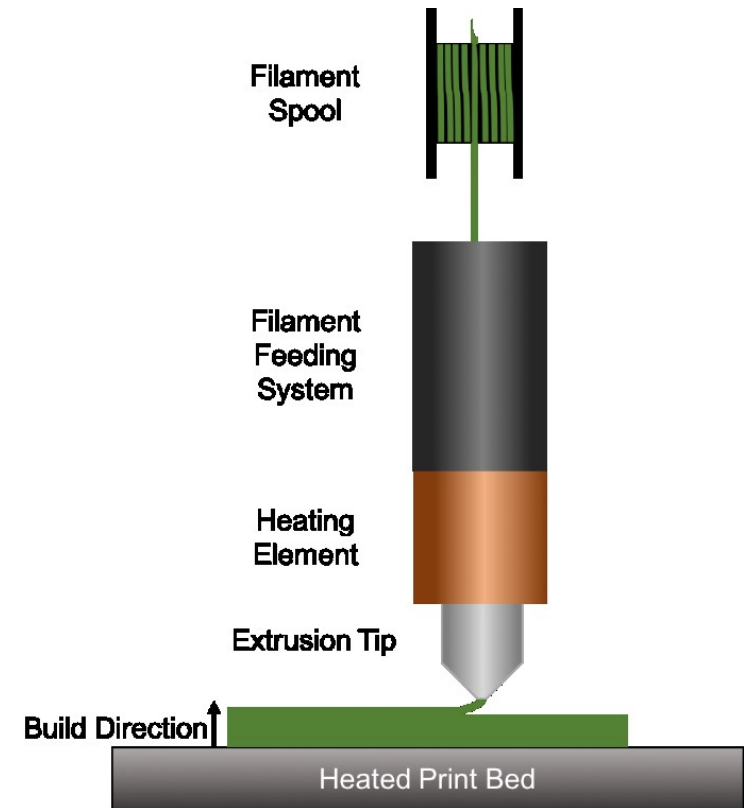


DDM Process: *FDM*

Video:

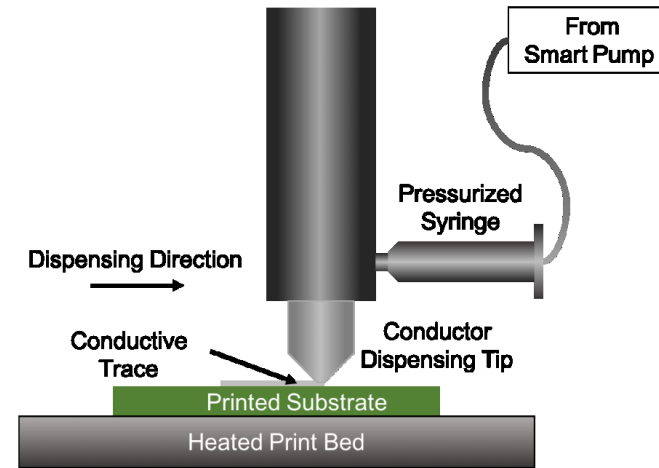


Typical nozzle temperature 200°C – 350°C
Minimum layer thickness ~50 microns

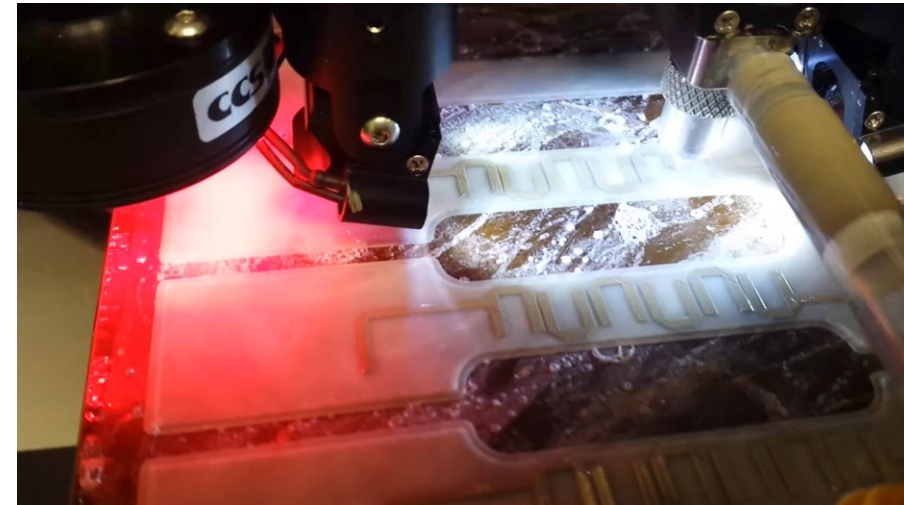
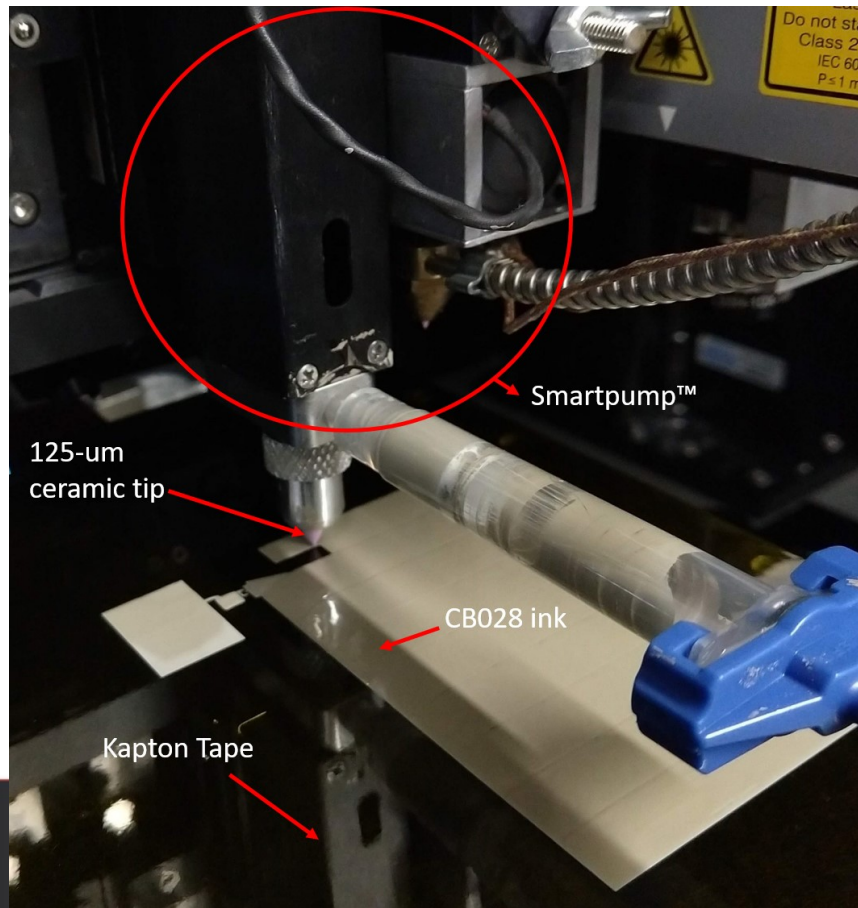


DDM Process: *Micro-Dispensing*

- Pastes such as Ag particle alloys used for conductors.
- Pressure, speed, etc. adjusted for desired feature sizes.
- Conformal printing using laser mapping.



Tip inner diameters:
250 μ m
125 μ m
75 μ m
25 μ m



Multilayer RF Electronics

2.45 GHz phased array antenna unit cell

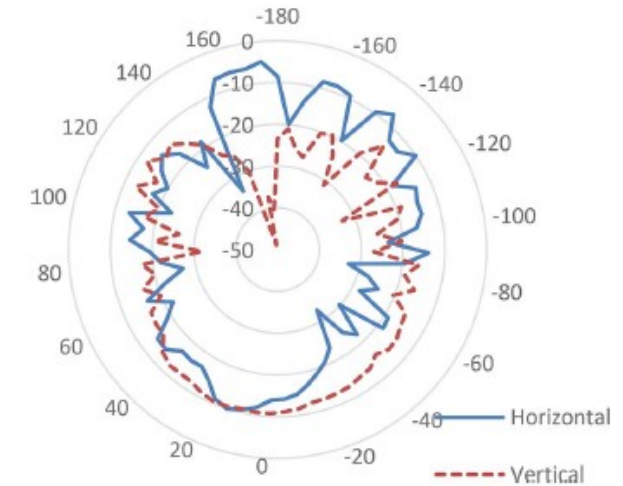
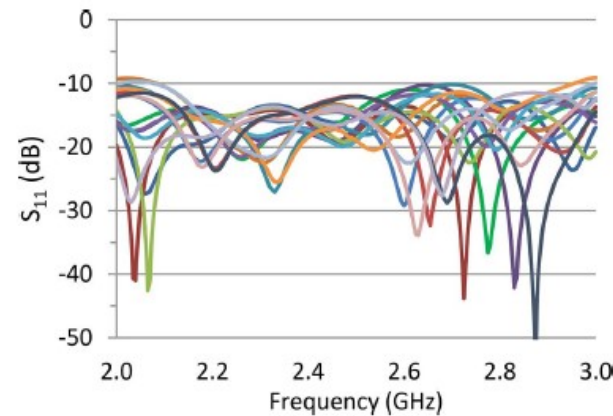
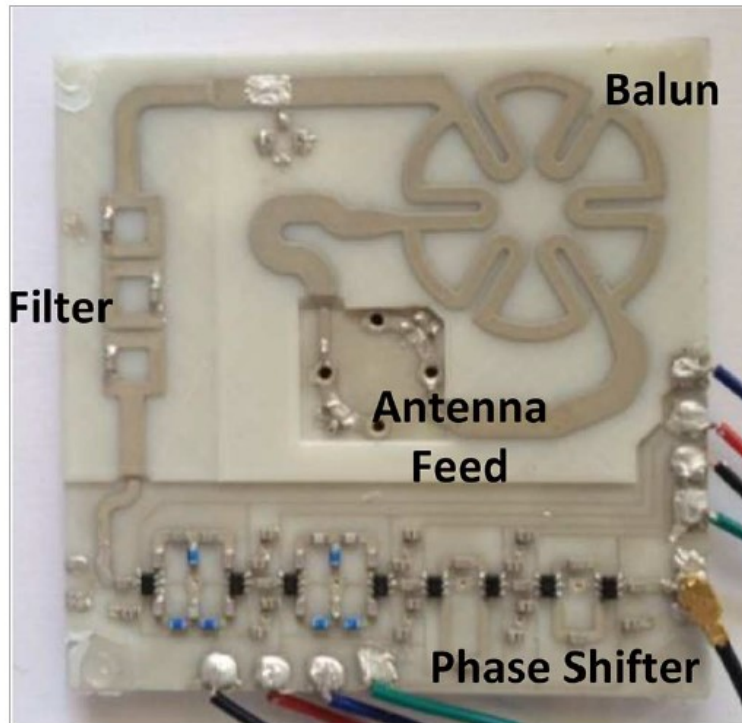
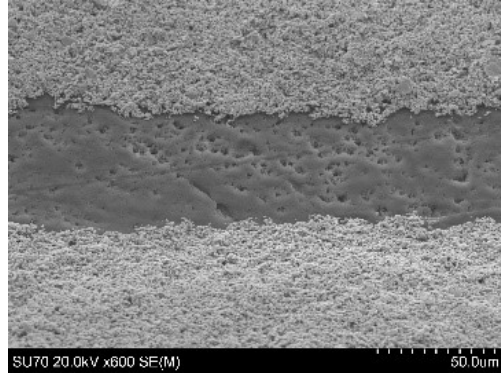


Fig. 24. Measured radiation patterns of the 2.45 GHz phased array unit cell. The vertical and horizontal gain pattern plots are shown.

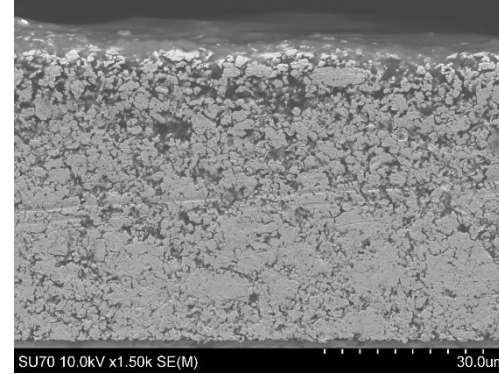
Thomas P. Ketterl, Yaniel Vega, Nicholas C. Arnal, John W. I. Stratton, **Eduardo A. Rojas-Nastrucci**, María F. Córdoba-Erazo, Mohamed M. Abdin, Casey W. Perkowski, Paul I. Deffenbaugh, Kenneth H. Church, and Thomas M. Weller, "A 2.45 GHz Phased Array Antenna Unit Cell Fabricated Using 3-D Multi-Layer Direct Digital Manufacturing," in *IEEE Transactions on Microwave Theory and Techniques*, vol. 63, no. 12, pp. 4382-4394, Dec. 2015.

Losses & Frequency Limits

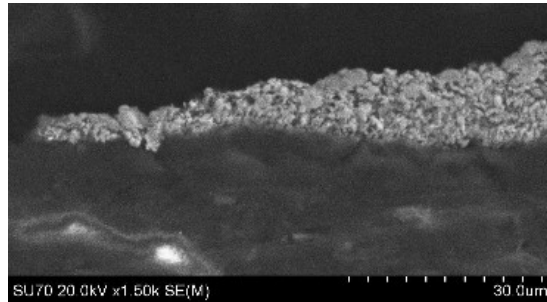
Surface roughness



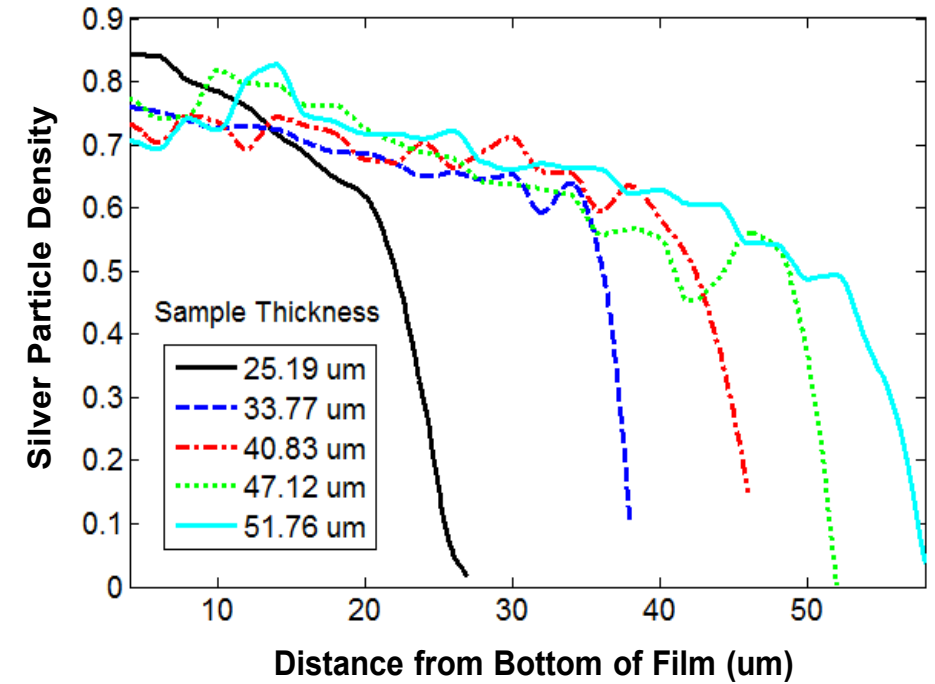
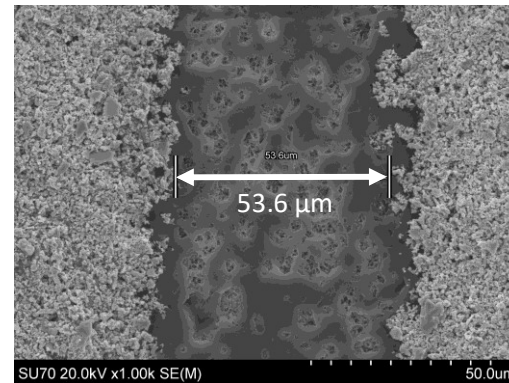
Non-uniformity



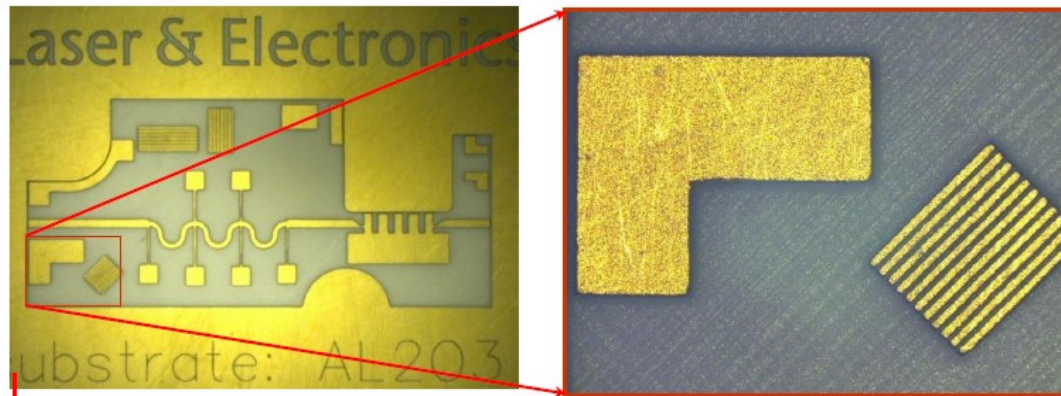
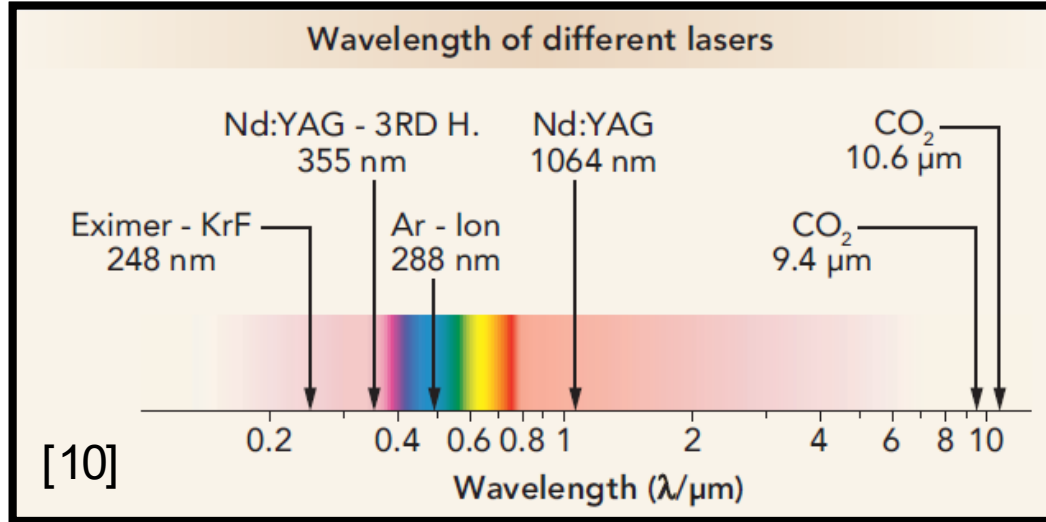
Tapered edges



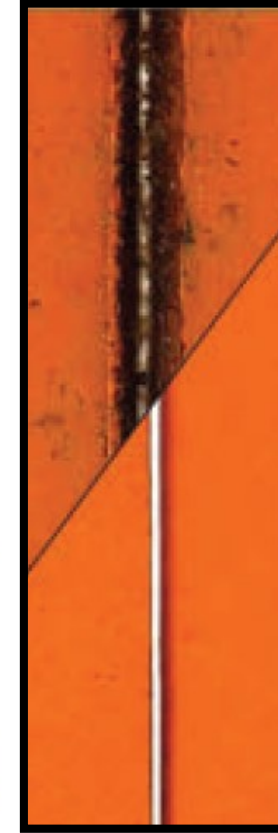
Maximum resolution of 50 μm



Laser Enhanced DDM



RF Applications LPKF - 25um cut



CO₂ (top) vs
Nd:YAG (bottom)
cut on Kapton

CO₂

- λ : 10.6 μ m
- Pulse width: ms to ns
- Local Heating, melting, material vaporization
- Thermal damage

Nd :Yag

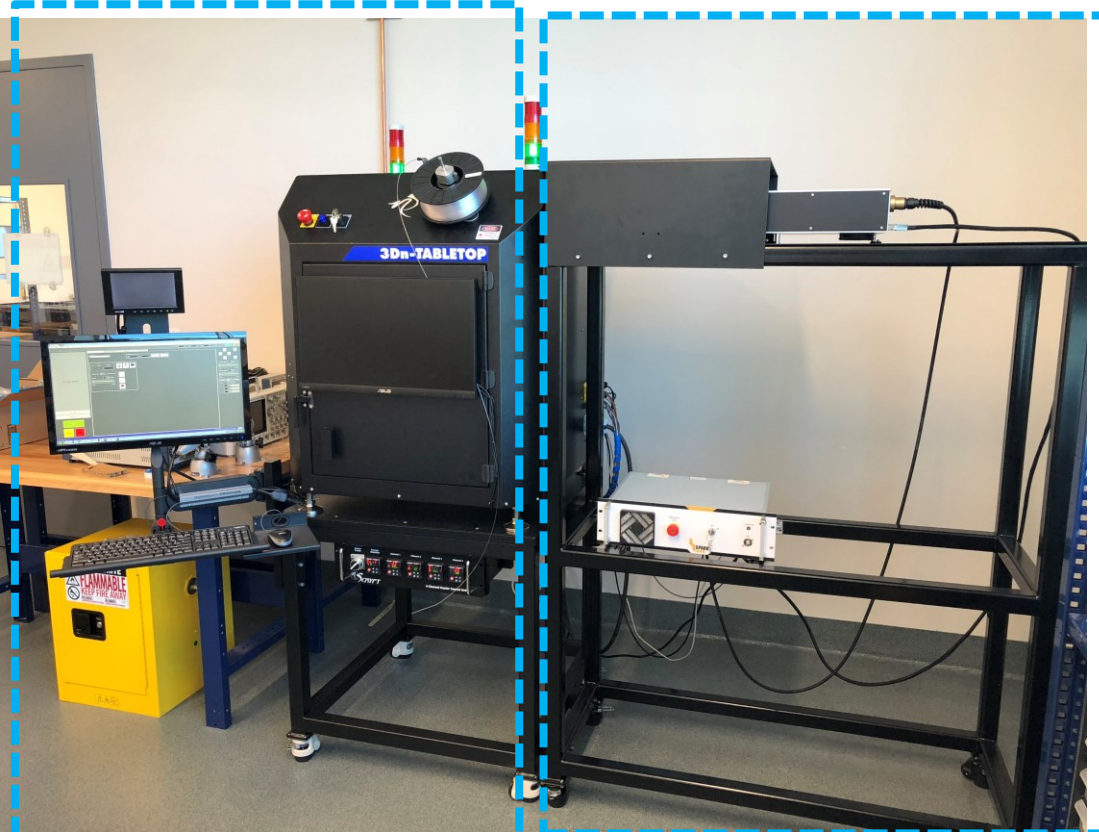
- λ : 1064 nm
- Pulse width: ps, fs
- Cold ablation
- Greatly reduced thermal damage

Laser Enhanced DDM

Femtosecond Laser Machining

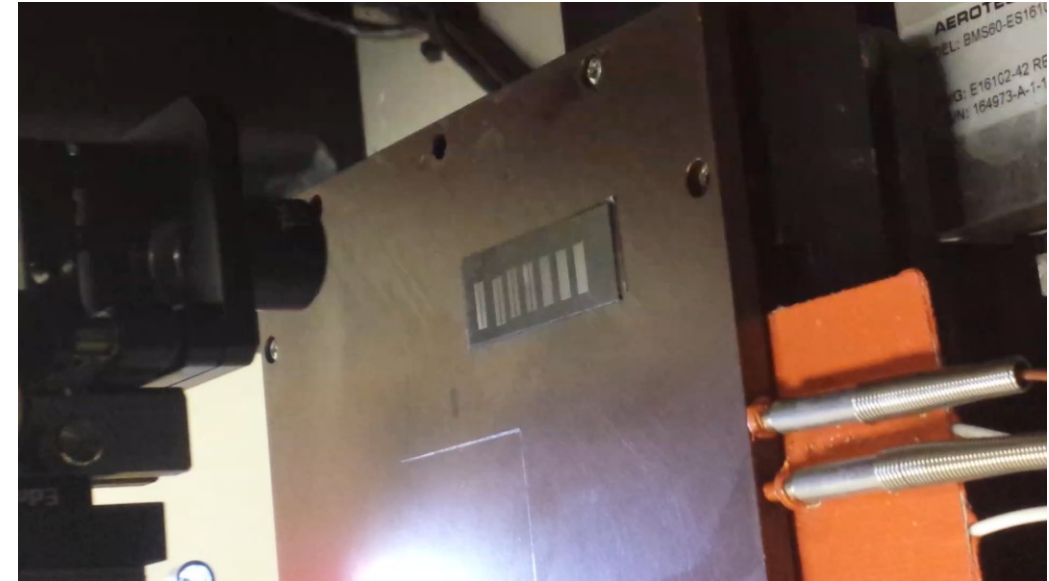
Lumera Nd:YAG

Laser machining process:



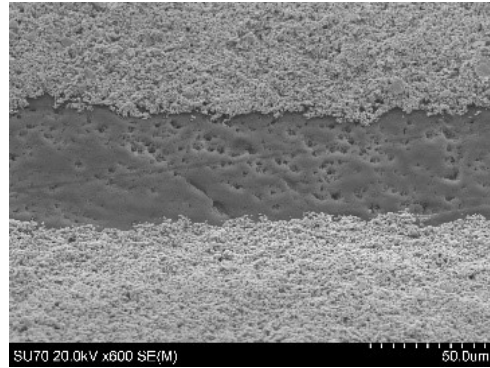
nScript DPAM system

Femtosecond Laser (10 W)

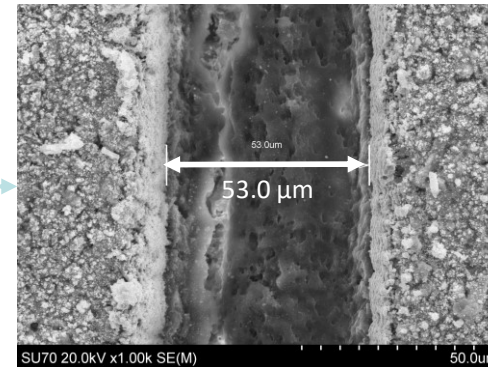
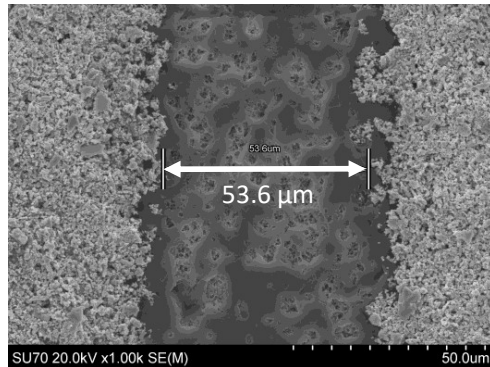
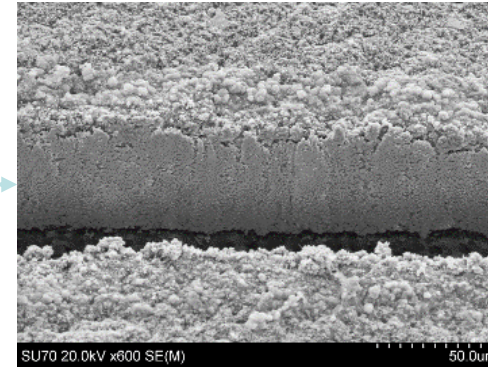


Laser Enhanced DDM

Micro-Dispensing



Micro-Dispensing + Laser Machining

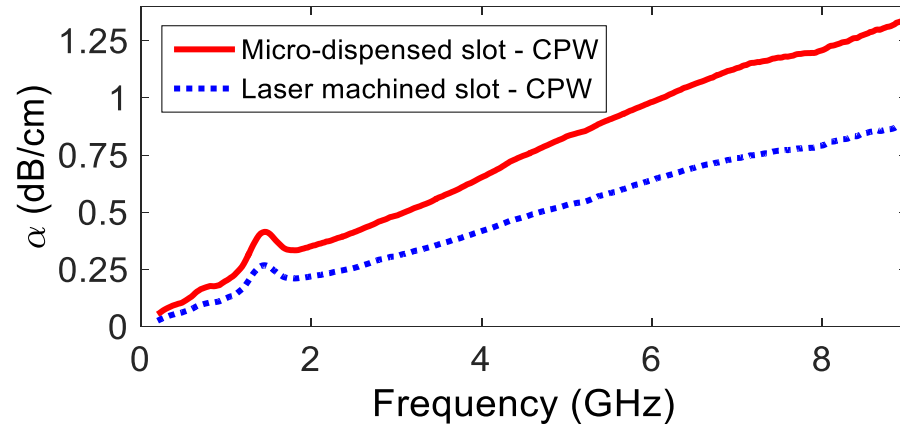


Pulsed ps Nd:YAG laser

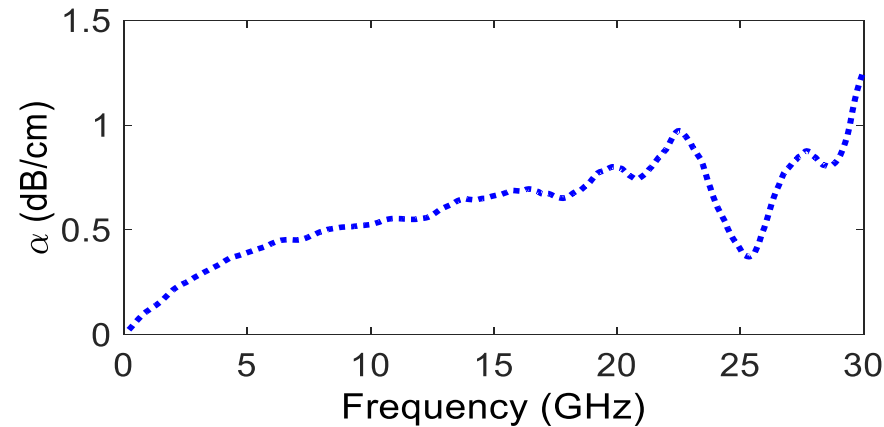
E. A. Rojas-Nastrucci, Harvey Tsang, Paul Deffenabugh, T. M. Weller, Ramiro A. Ramirez, D. Hawatmeh, and Kenneth Church, "Characterization and Modeling of K-Band Coplanar Waveguide Digitally Manufactured using Pulsed Picosecond Laser Machining of Thick-Film Conductive Paste," in *IEEE Transactions on Microwave Theory and Techniques*, vol. 65, no. 9, pp. 3180-3187, Sept. 2017.

Laser Enhanced DDM

Loss of CPW with slot size of 50 μm



Loss of CPW with slot size of 20 μm



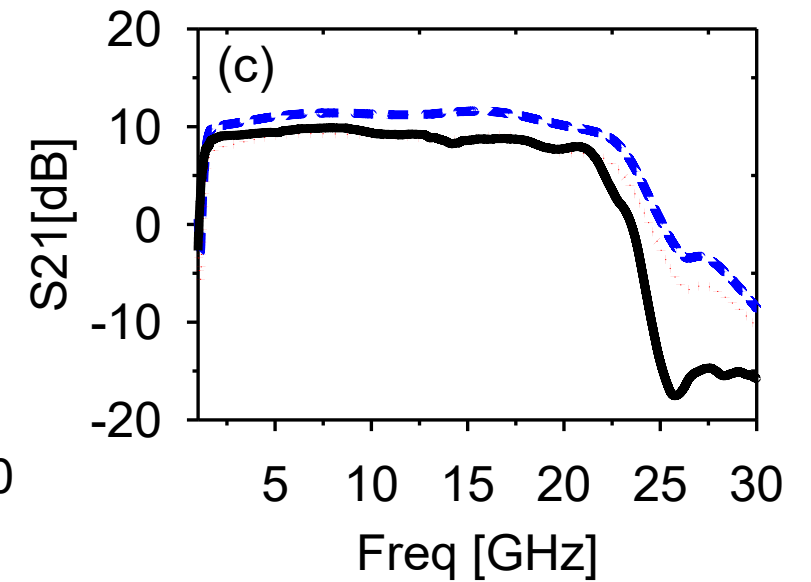
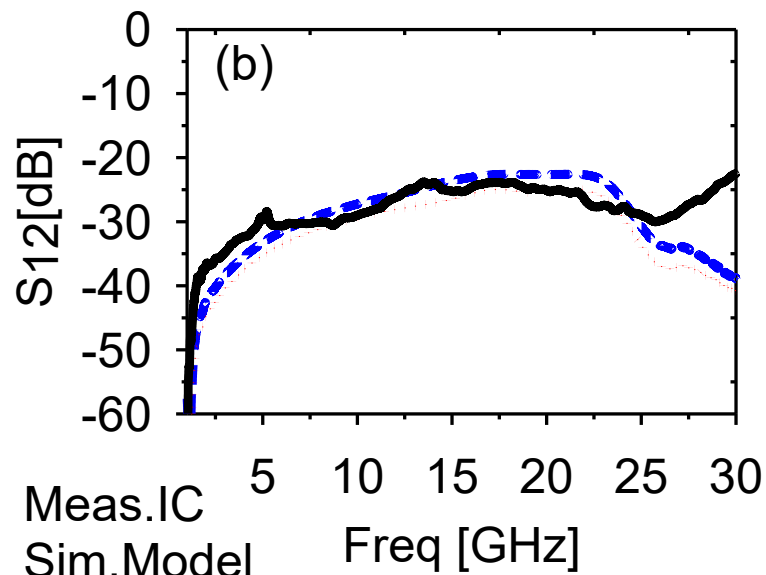
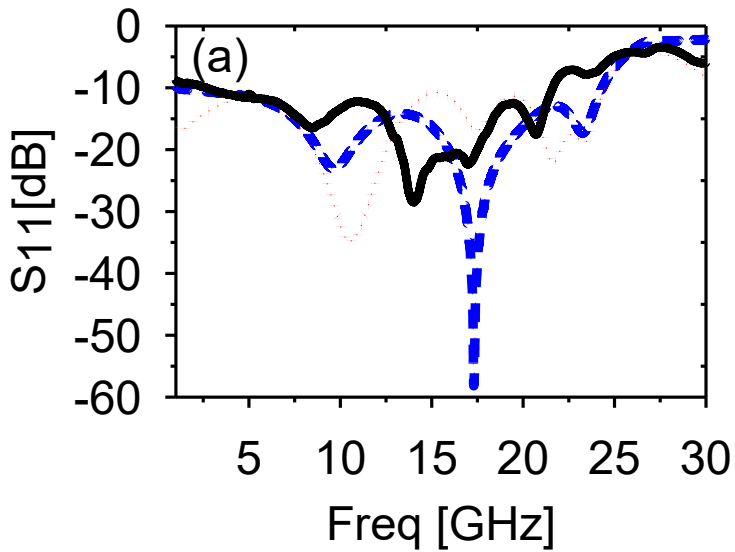
Micro-dispensed CB028: $\sigma_{\text{eff}} < 1\text{e}6 \text{ S/m}$

Laser machined CB028: $\sigma_{\text{eff}} > 1\text{e}7 \text{ S/m}$

Attenuation comparable to Cu cladding

E.A. Rojas-Nastrucci, Harvey Tsang, Paul Deffenabugh, T. M. Weller, Ramiro A. Ramirez, D. Hawatmeh, and Kenneth Church, "Characterization and Modeling of K-Band Coplanar Waveguide Digitally Manufactured using Pulsed Picosecond Laser Machining of Thick-Film Conductive Paste," in *IEEE Transactions on Microwave Theory and Techniques*, vol. 65, no. 9, pp. 3180-3187, Sept. 2017.

Simulated & Measured Data



-- Meas.IC
..... Sim.Model
— Meas.Package

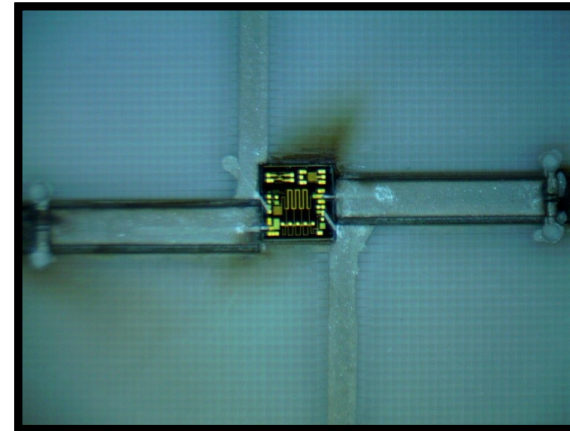
T-Line Attenuation

5 GHz – 0.125 dB/mm

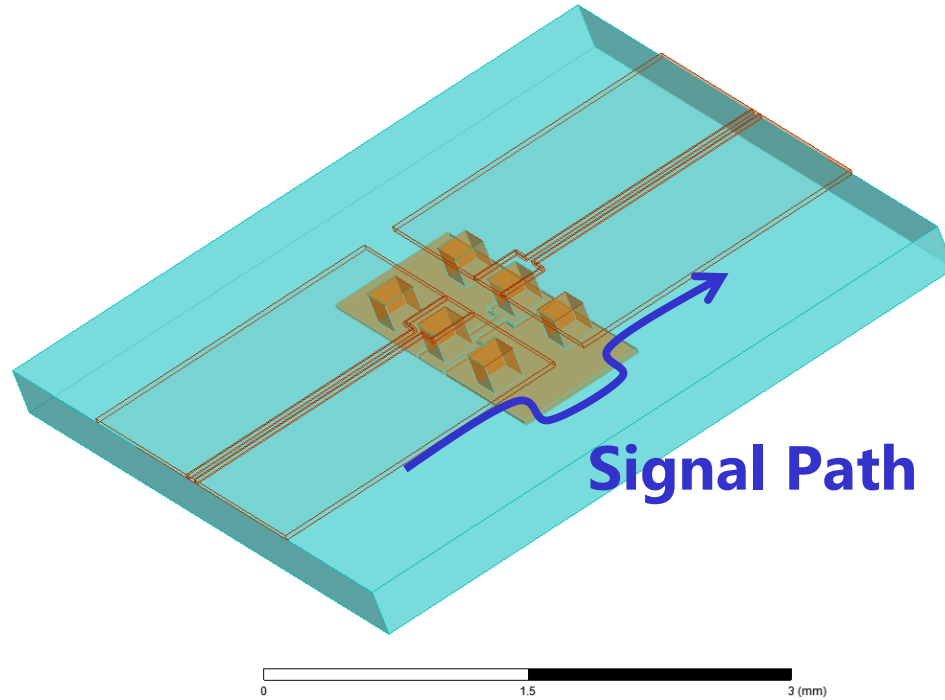
20 GHz – 0.2 dB/mm

Return loss

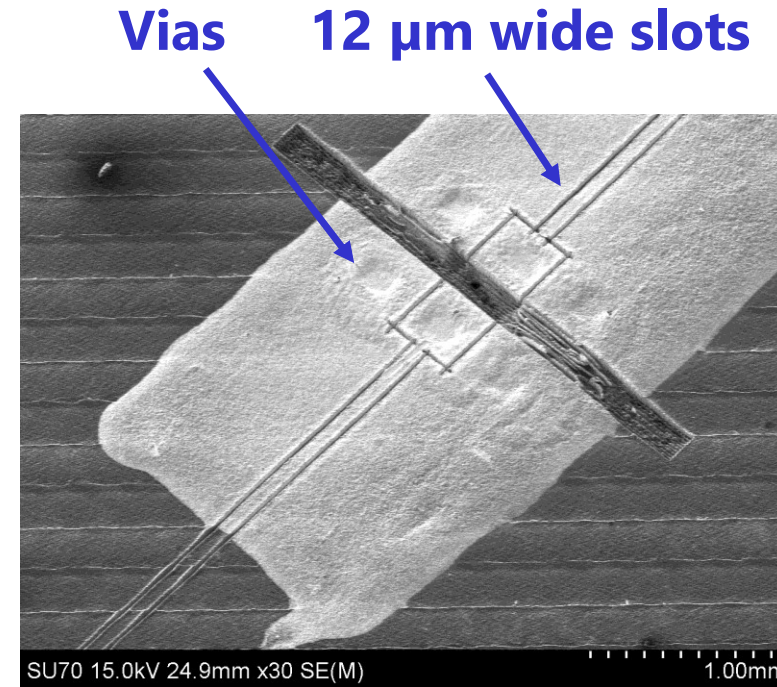
10 dB – within frequency band of interest



DDM Multi-Layer Interconnects



Simulated Structure

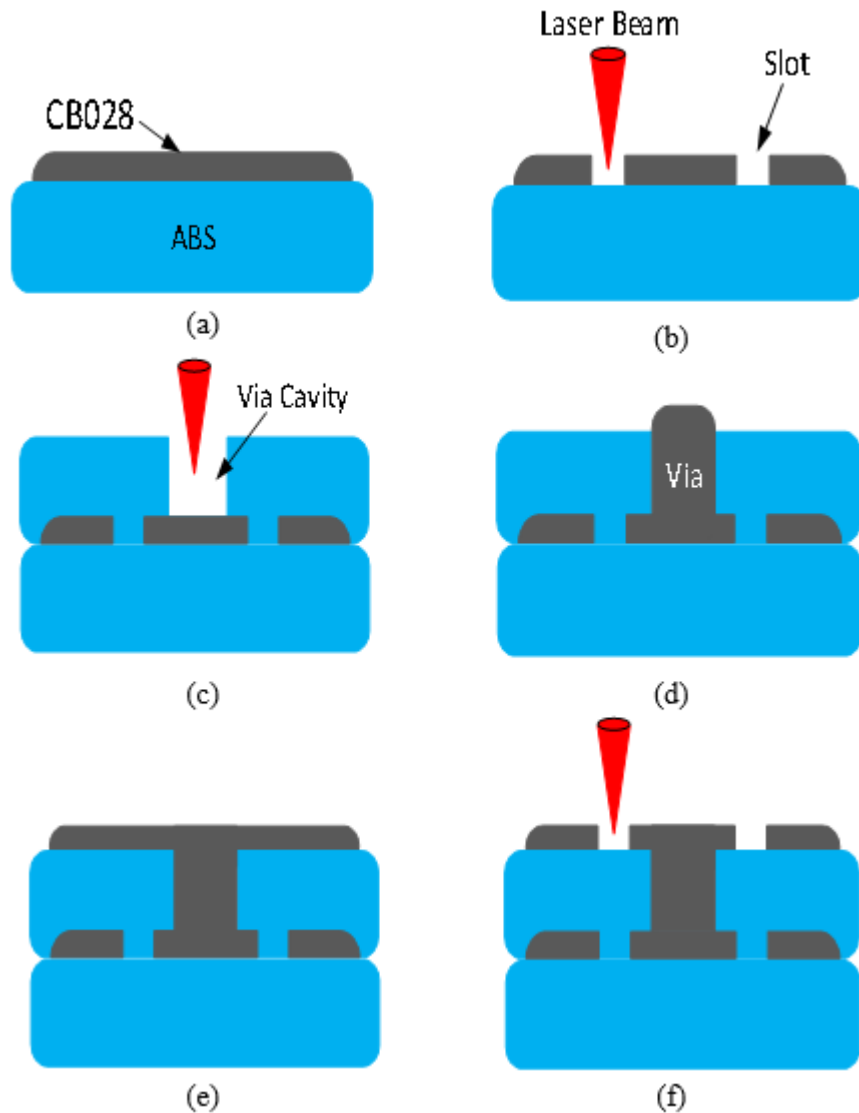


Fabricated Structure

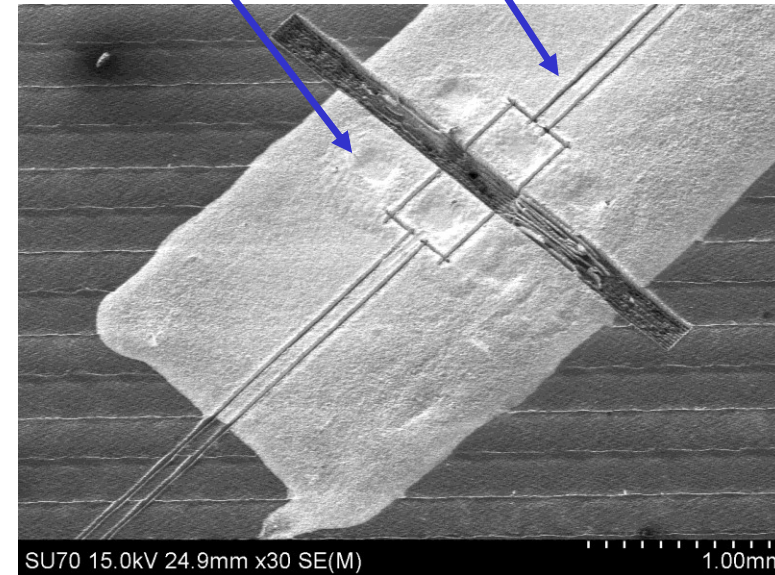
- Dielectric layers are ABS with a thickness of 50 μm .
- CB028 micro-dispensed with a typical layer thickness of 25 μm
- Traces are machined using picosecond laser, achieving 12 μm wide slots.

DDM Multi-Layer Interconnects

Process

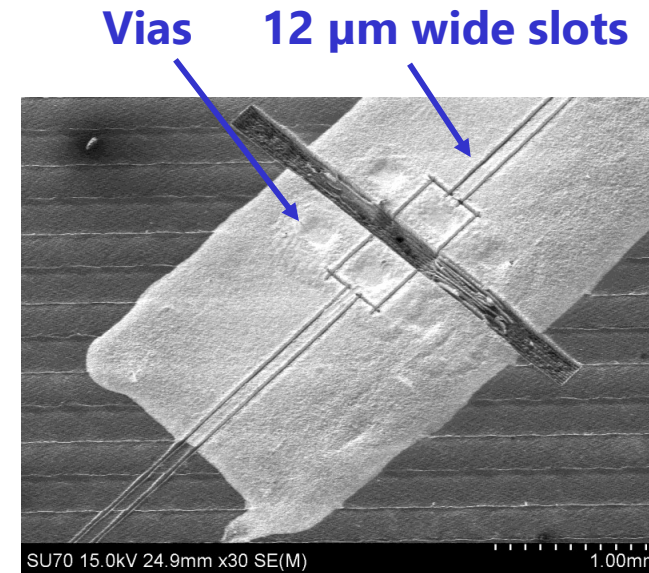
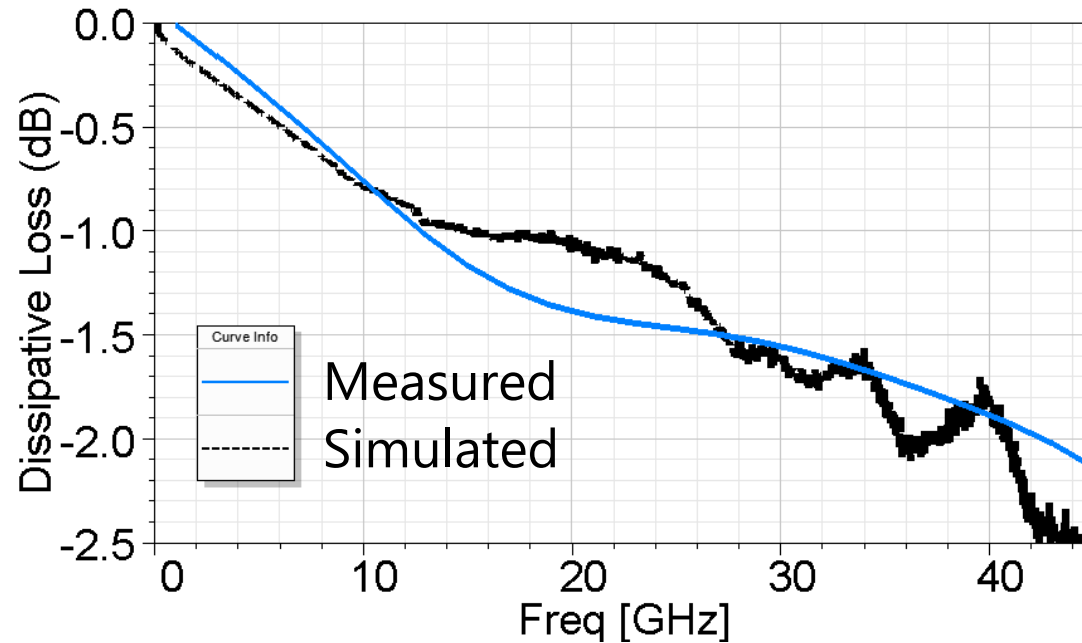


Vias 12 μm wide slots



Fabricated Structure

DDM Multi-Layer Interconnects



Fabricated Structure

- Test structure that includes two CPW vertical transitions shows 4.25 dB/cm of loss at 40 GHz.

Novel Sensing Mechanisms

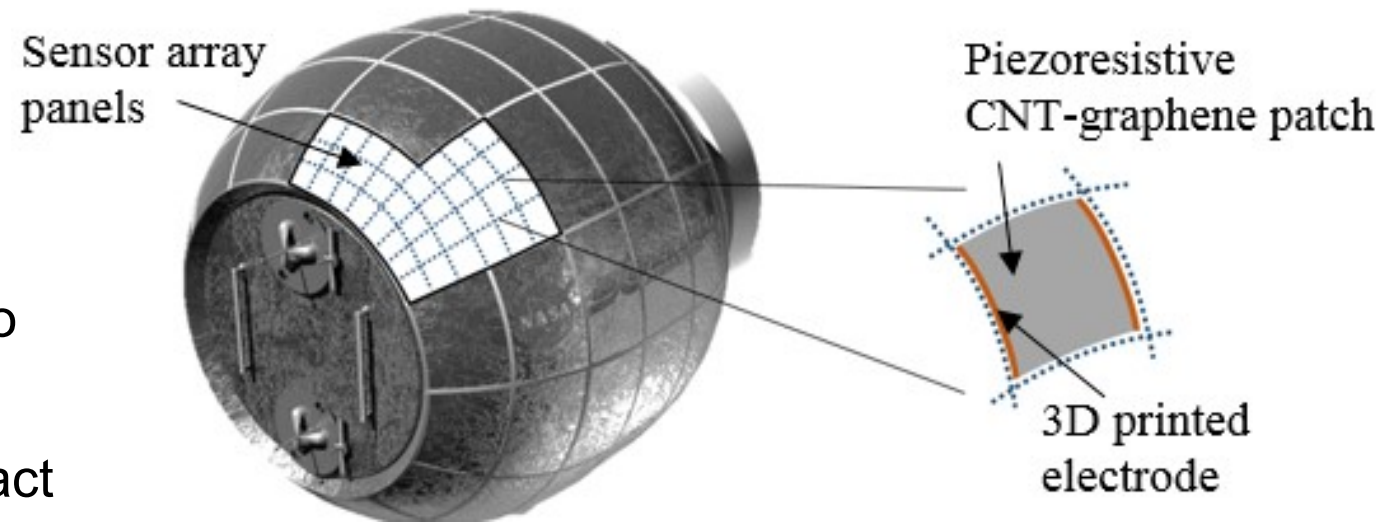
Sensor developed by Daewon Kim and Srish Namilae

- **Objective**

Develop an MMOD impact detection system that can be incorporated into the inflatable structure. An integrated SHM system should provide existence and location of damage, depth of penetration, and damage extent.

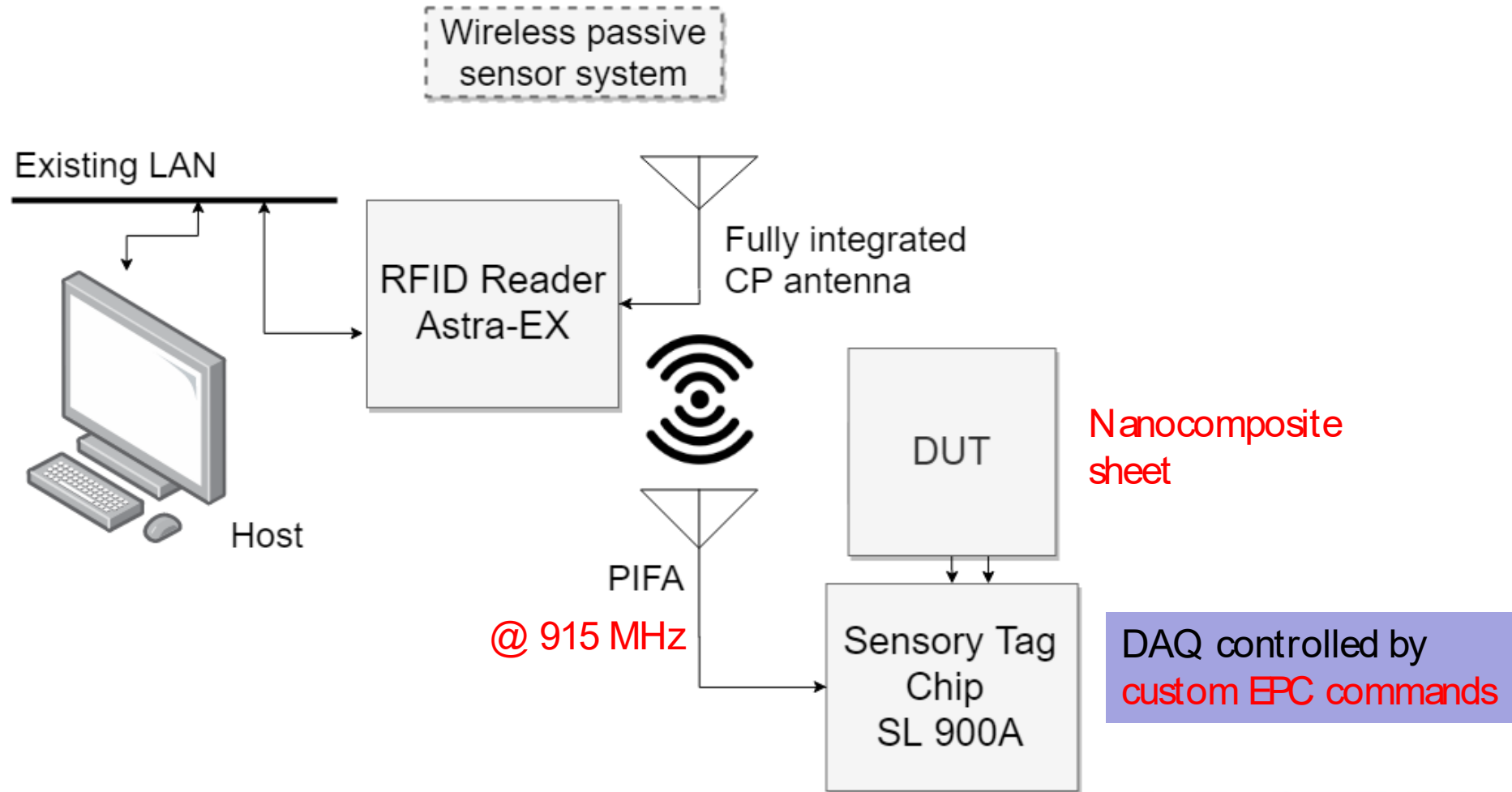
- **Approach**

- Develop flexible piezoresistive sensors composed of carbon nanotubes sheet and coarse graphene platelets.
- Perform static and dynamic impact testing to measure sensor performance.
- Perform multi-sensors and multi-layers impact testing to prove MMOD detection capabilities.



Design of the Wireless Passive Sensor

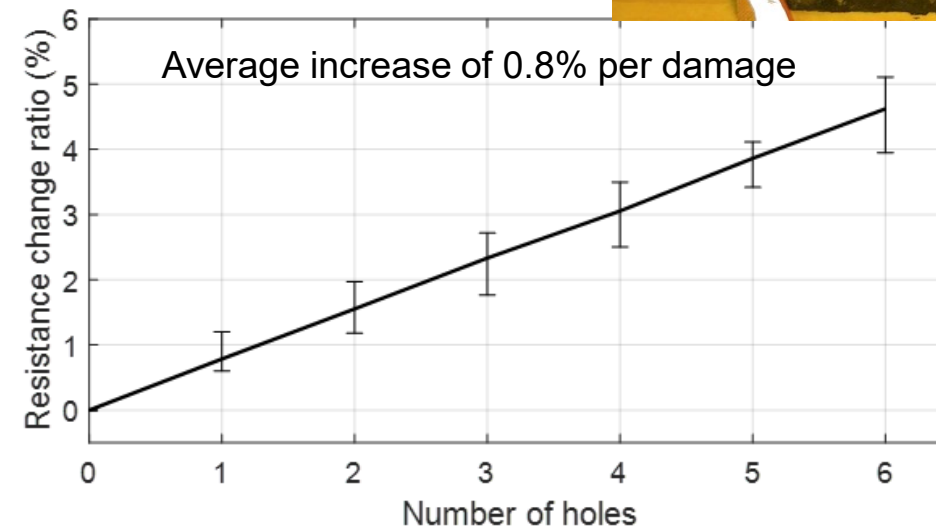
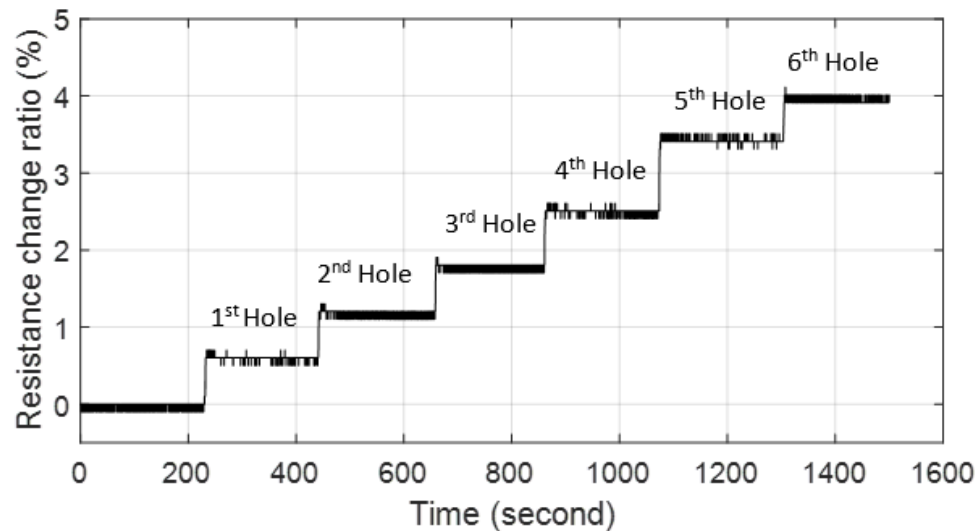
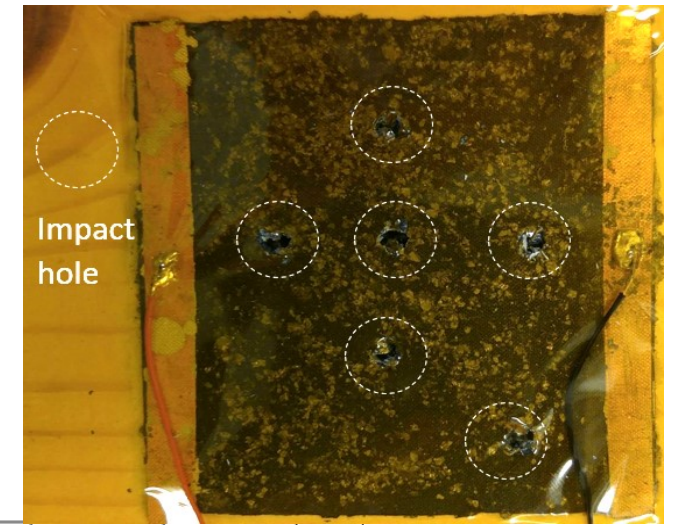
Overall system based on RFID technology



Sensor - Static Puncture Testing

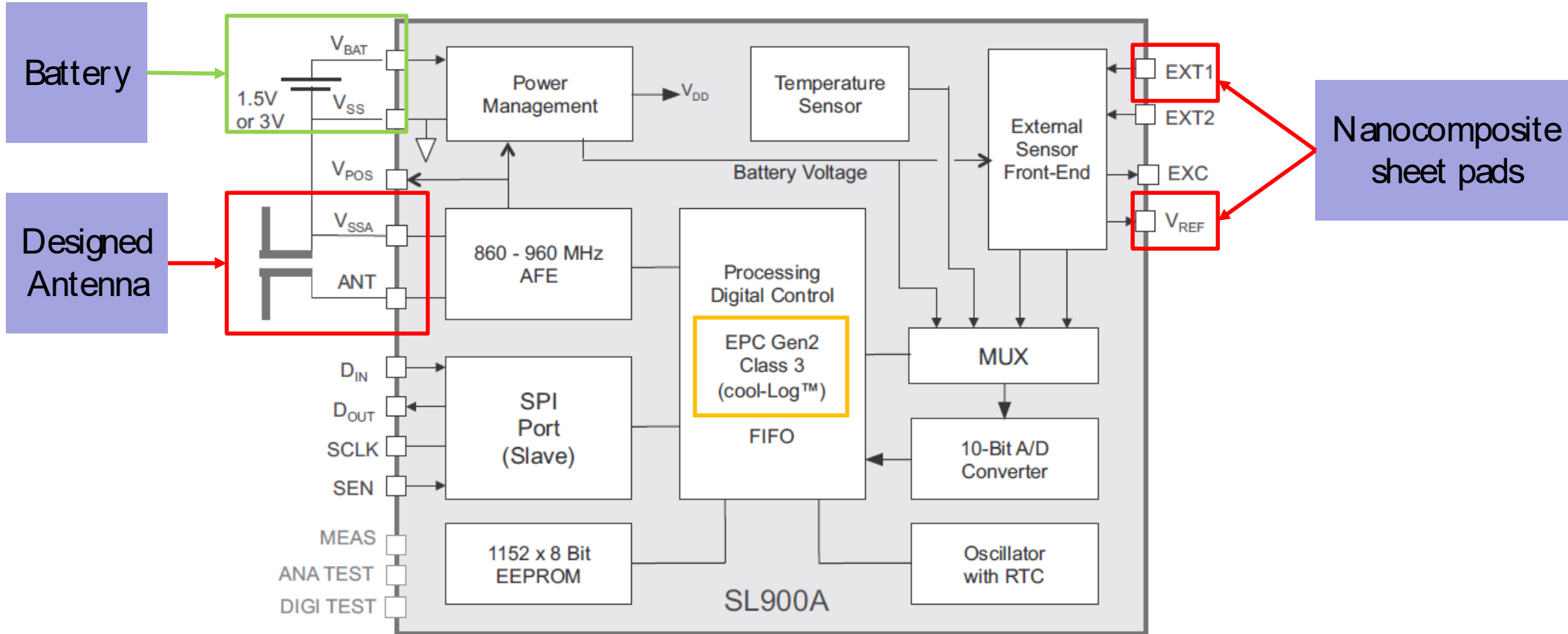
Sensor developed by Daewon Kim and Srish Namilae

- Resistivity with multiple holes
 - 2.5 in x 2.5 in nanocomposites covered with Kapton tape; six holes are successively added.
 - Change in resistance when subject to static damage induced by drilling 3 mm holes.
 - Resistance remains constant with added holes → stable



Design of the Wireless Passive Sensor

Basic block diagram of the IC sensory tag



Credits: AMS

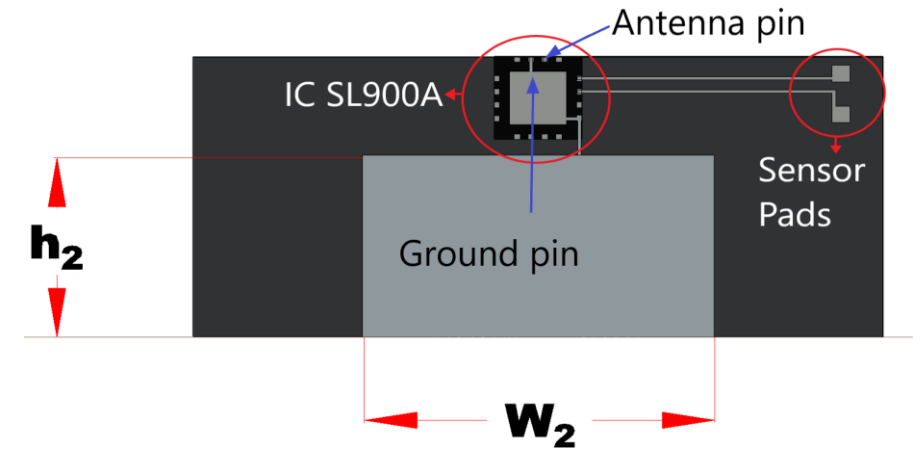
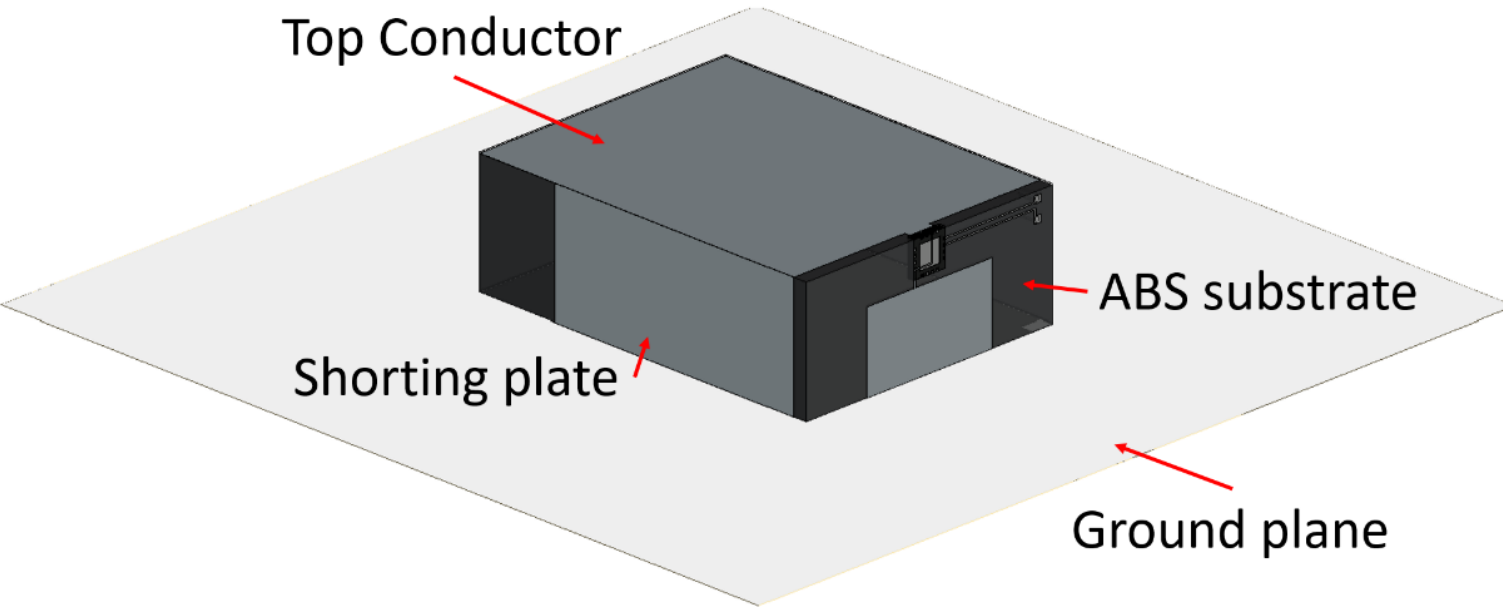
Design of the Wireless Passive Sensor

Features of the IC sensory tag

Electrical Characteristics	Value
Antenna pad impedance	123-j303 Ω
Antenna pad sensitivity	-6.9 dBm
Antenna pad sensitivity (Battery assisted)	-15 dBm
Carrier frequency	860 MHz to 960 MHz
External sensor interface pads resistance	200 Ω

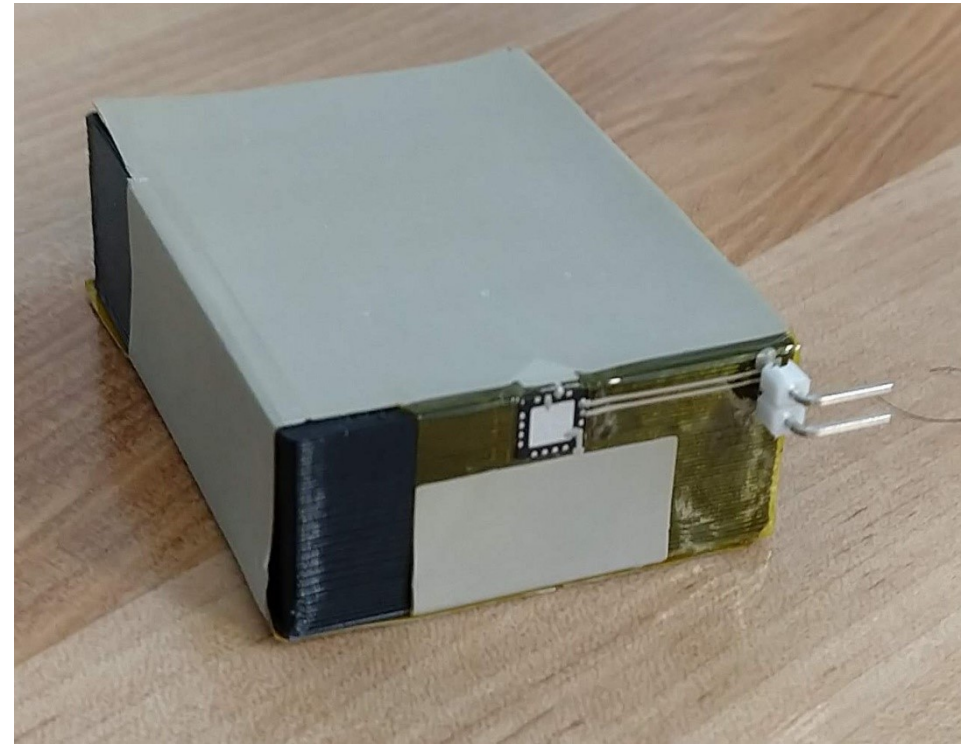
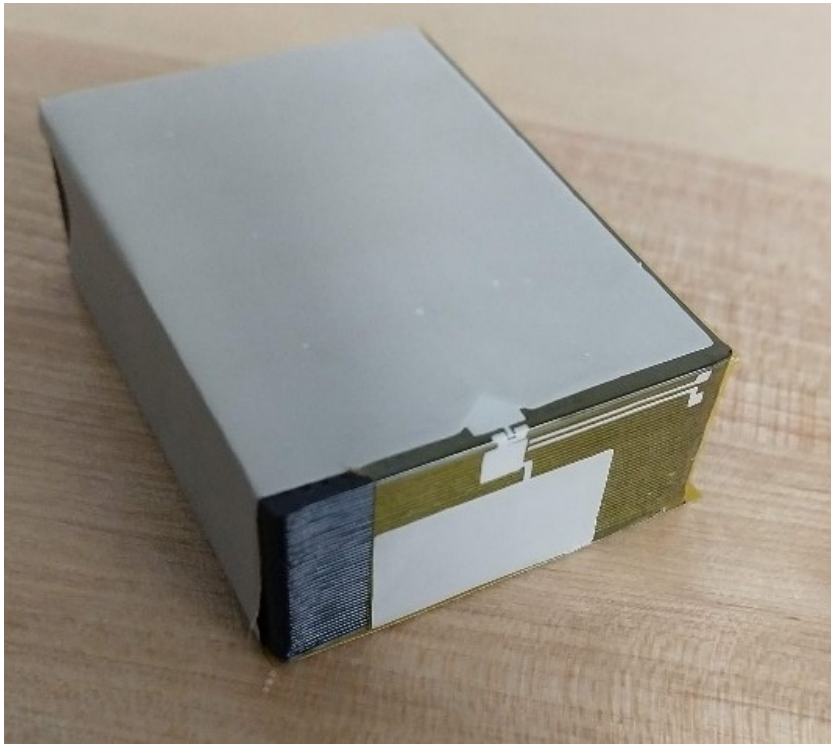
Design of the Wireless Passive Sensor

Electrically small antenna (ESA) based on a PIFA design



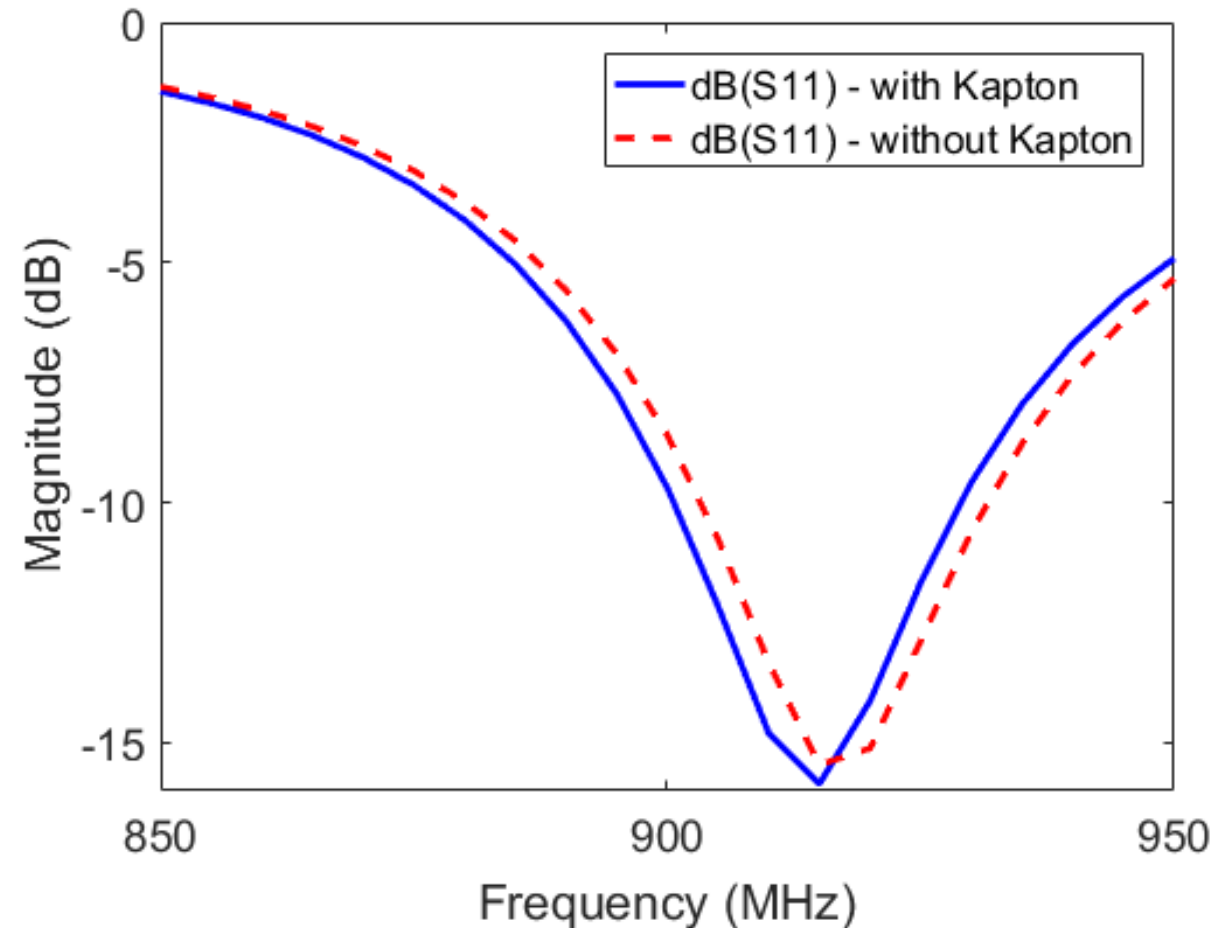
Design of the Wireless Passive Sensor

Fabricated Sensor



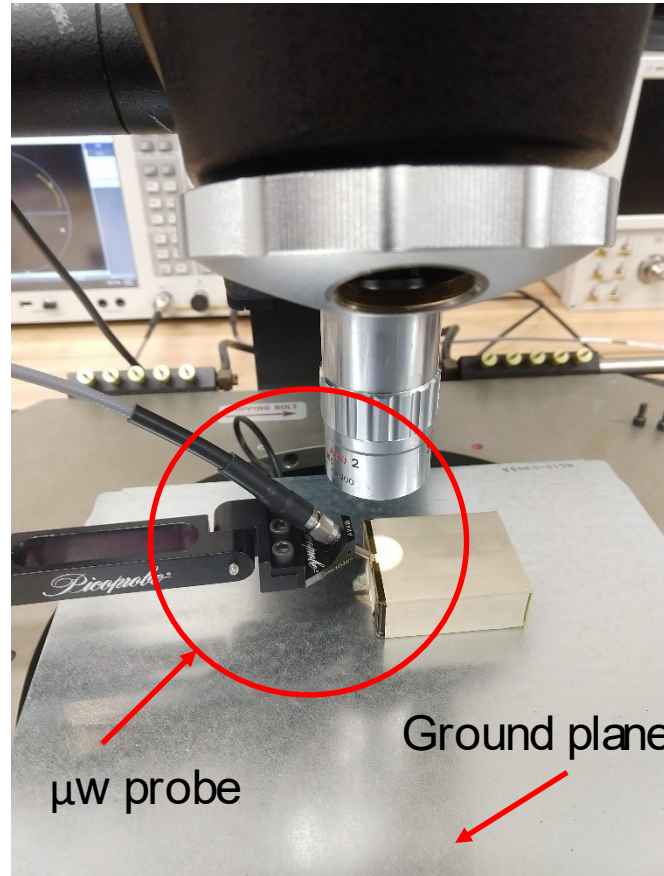
Design of the Wireless Passive Sensor

Effect of Kapton wrapping on S11



Results - Wireless Passive Sensor

S11 response measurement

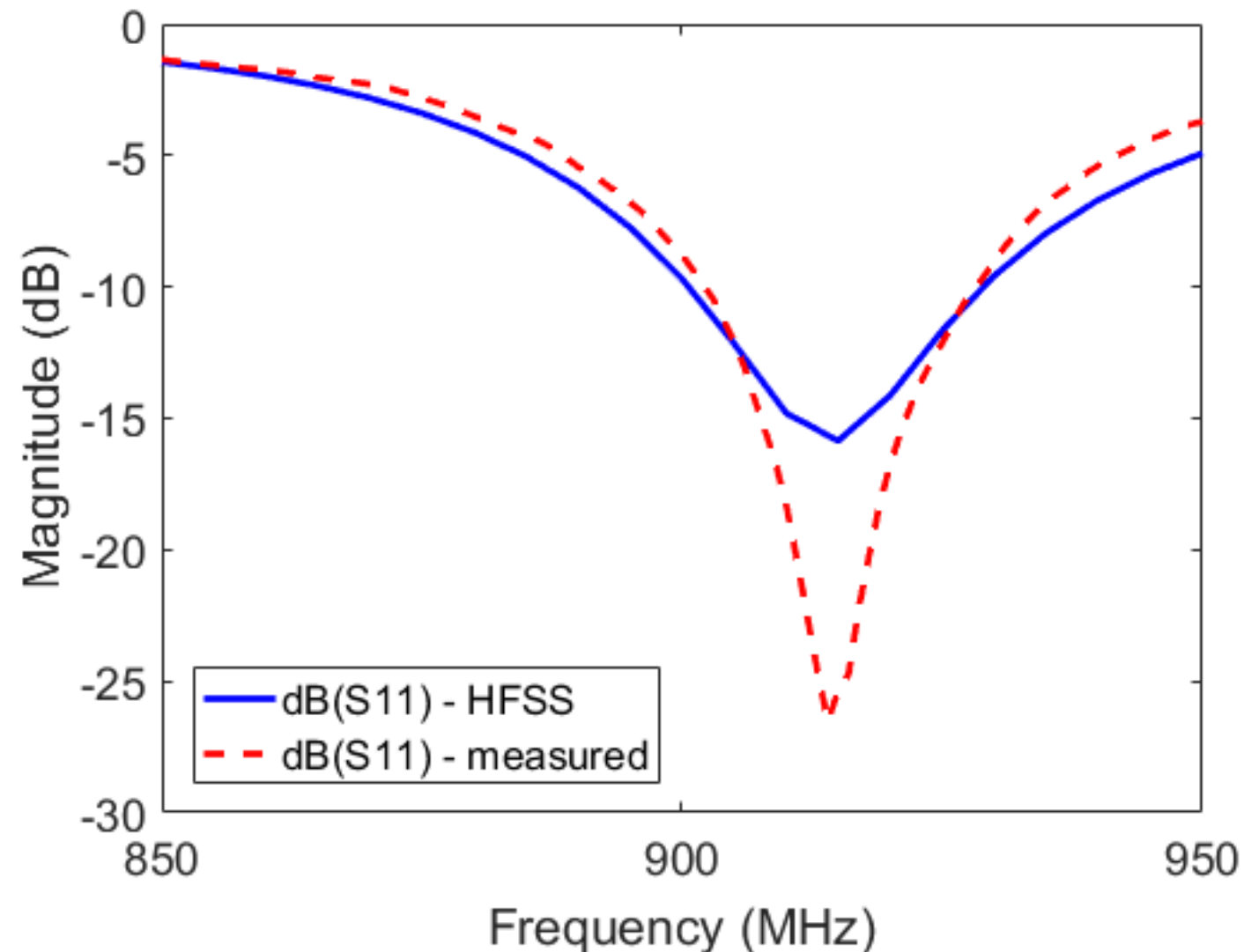


Measuring fixture:

- Gap: 0.4 mm
- Width: 0.2 mm
- Length: 0.4 mm

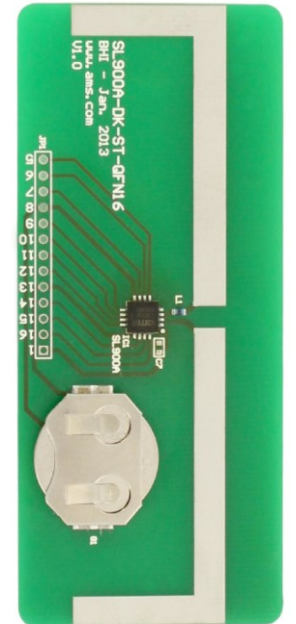
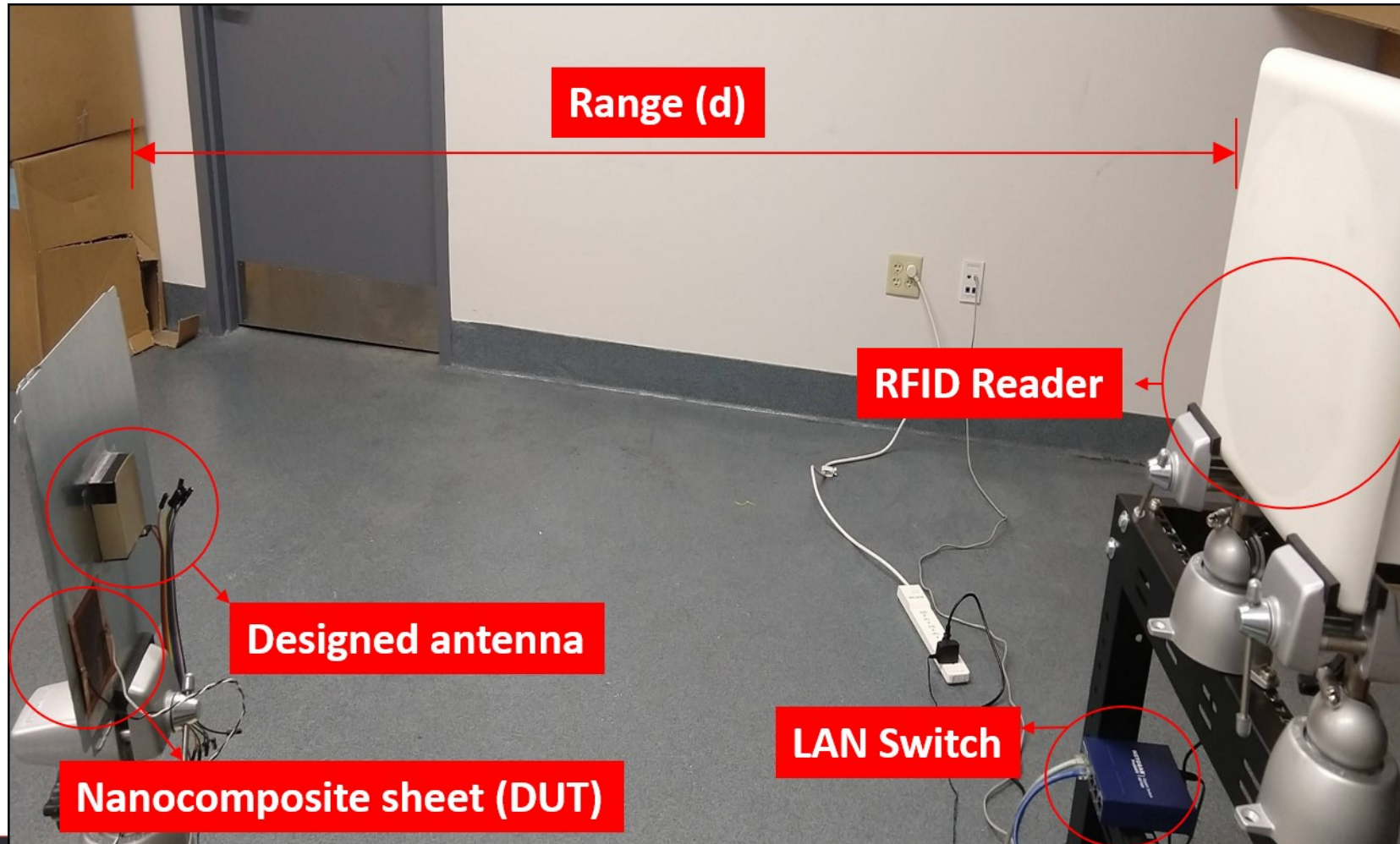
Results - Wireless Passive Sensor

S_{11} measured



Design of the Wireless Passive Sensor

Set-up for measuring the range of the passive wireless



AMS SL900A
Demo Board

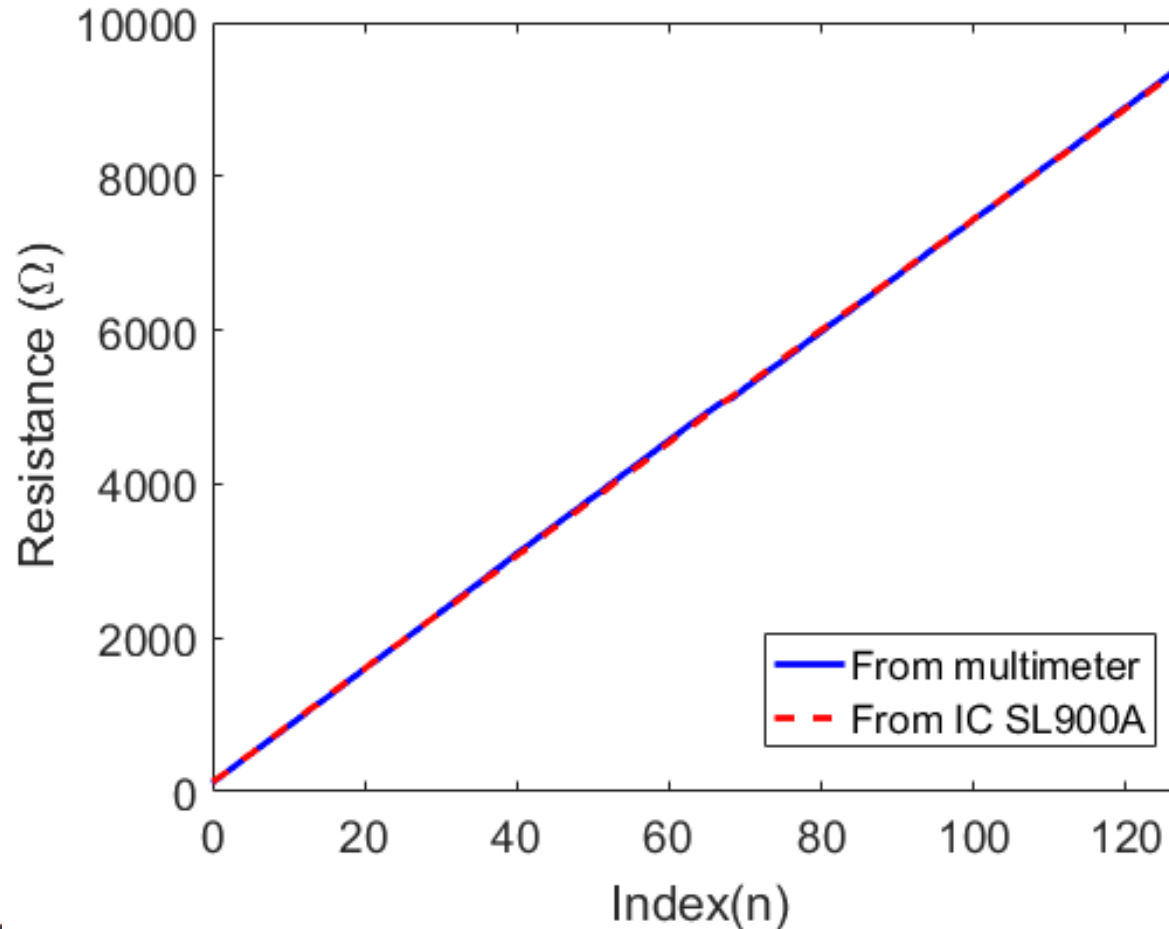
Results - Wireless Passive Sensor

Sensor range for AMSdemo board and the designed antenna

	Detection (m)	Sensing (m)
AMSDemo Board	3.8	1.4
AMSDemo Board (Battery assisted)	12.4	2.6
Designed antenna	3.2	1.9

Results - Wireless Passive Sensor

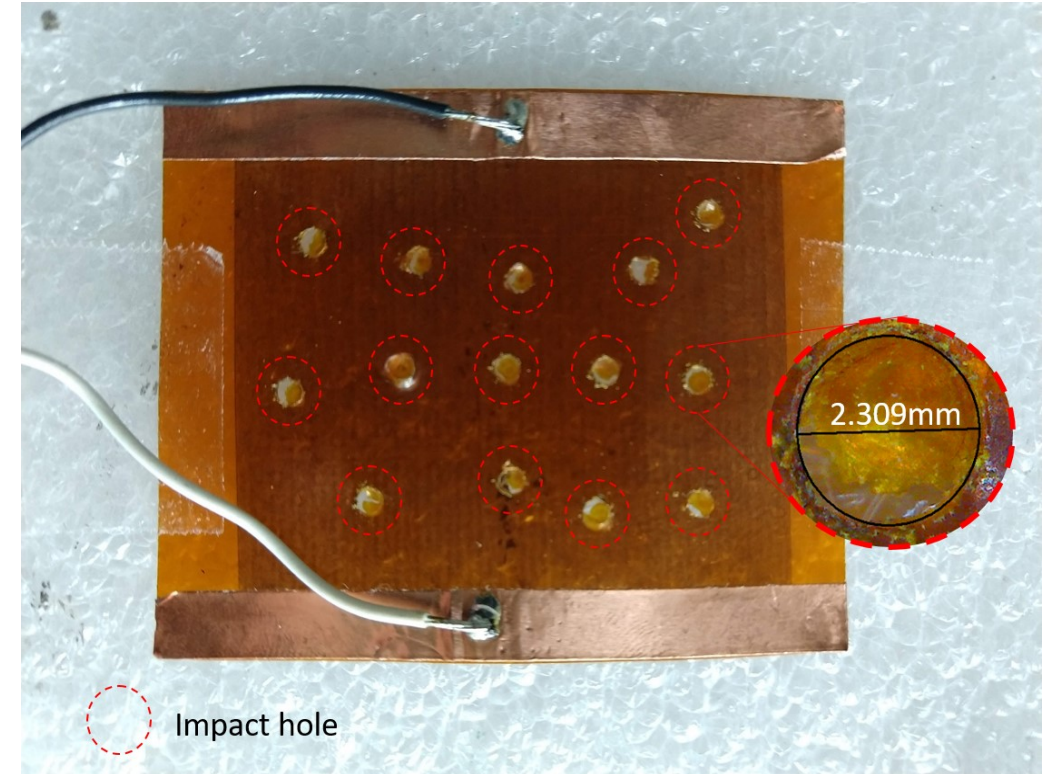
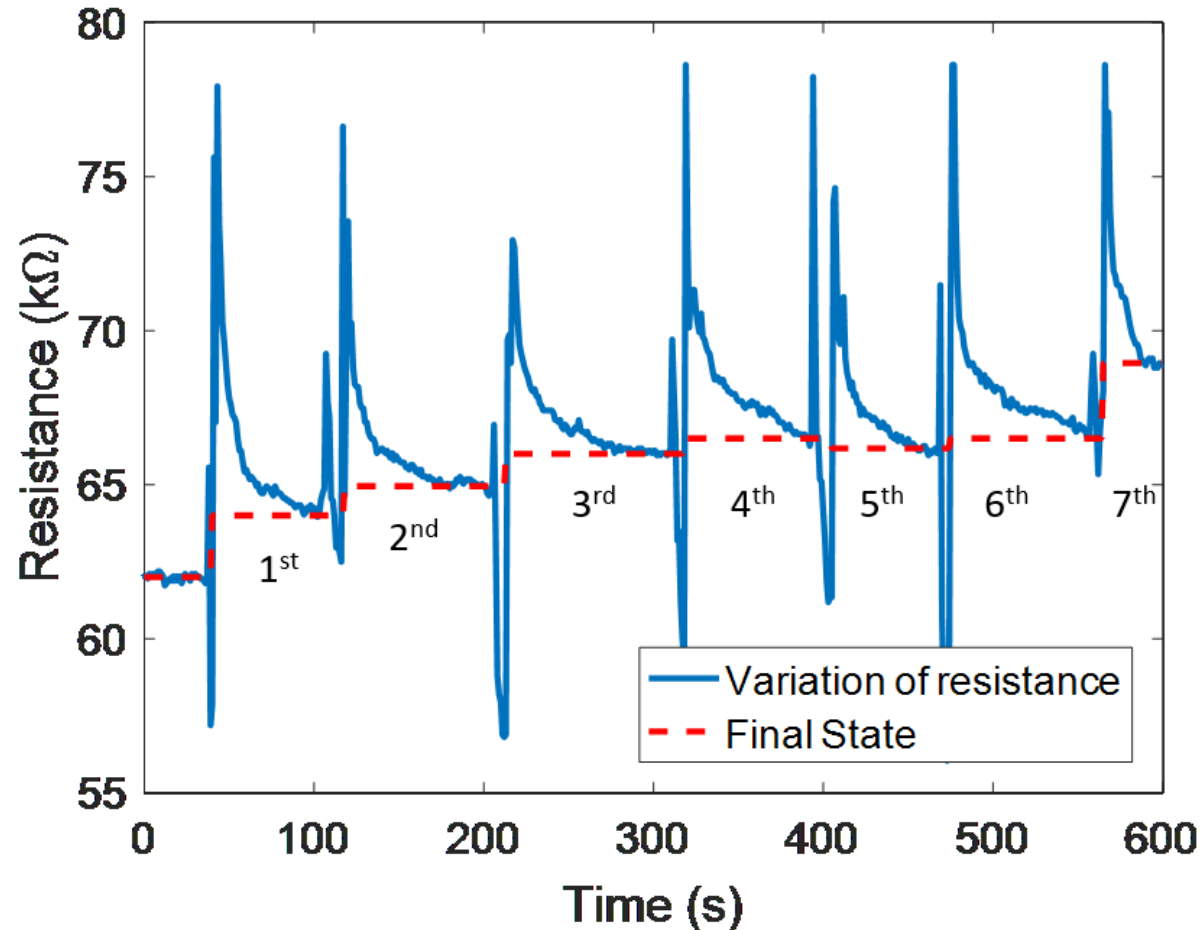
Resistance sensing using the wireless passive sensor



Mean error: 1%
Max error: 22%

Results - Wireless Passive Sensor

Resistance change of the nanocomposite sheet – Static damage



Research Park



WiDE Lab

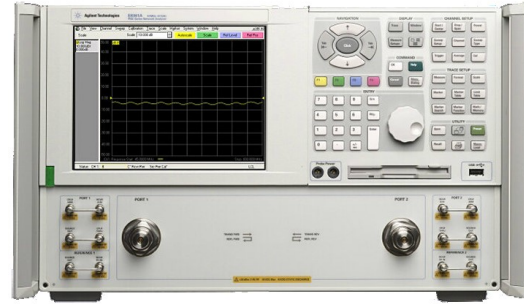
ERAU
Micaplex



4200 sq. ft of
RF Labs



Capabilities - Hardware



Keysight PNA (67 GHz)



ETSAMS-8500 Anechoic Chamber
(12 ft x 12 ft x 24 ft)



LPKF Laser PCB Mill



RF Probing



nScript DPAM system Femtosecond Laser (10 W)

Capabilities – Test Beds

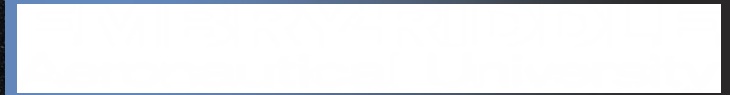
Gulfstream GIII



Learjet



Turbines



Acknowledgements

Dr. Thomas Weller, Dr. Jng Wang, Dr. Ramiro Ramirez, Dr. Di Lan, Dr. Daewon Kim, Dr. Sirish Namilae, Dr. Ken Church, Dr. Paul Deffenbaugh



I thank you

